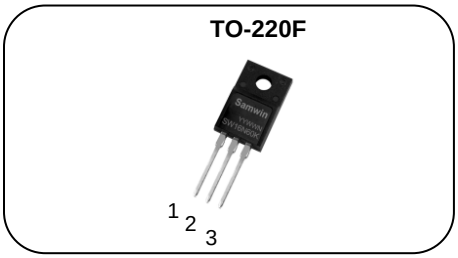
Samwin®

SW16N60K

N-channel Enhanced mode TO-220F MOSFET

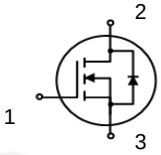
Features

- High ruggedness
- Low $R_{DS(ON)}$ (Typ 0.21Ω)@V_{GS}=10V
- Low Gate Charge (Typ 43nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application:LED, Charger, PC Power



1. Gate 2. Drain 3. Source

BV_{DSS} : 600V
I_D : 16A
$R_{DS(ON)}$:0.21Ω



General Description

This power MOSFET is produced with advanced super junction technology of SAMWIN. This technology enable the power MOSFET to have better characteristics, including fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.

Order Codes

Item	Sales Type	Marking	Package	Packaging
1	SW F 16N60K	SW16N60K	TO-220F	TUBE

Absolute maximum ratings

Symbol	Parameter		Value	Unit
V_{DSS}	Drain to source voltage		600	V
I_D	Continuous drain current (@T_C=25°C)		16*	A
	Continuous drain current (@T_C=100°C)		10*	A
I_{DM}	Drain current pulsed	(note 1)	48	A
V_{GS}	Gate to source voltage		±30	V
E_{AS}	Single pulsed avalanche energy	(note 2)	300	mJ
E_{AR}	Repetitive avalanche energy	(note 1)	16	mJ
dv/dt	MOSFET dv/dt ruggedness (@VDS=0~400V)		30	V/ns
dv/dt	Peak diode recovery dv/dt	(note 3)	20	V/ns
P_D	Total power dissipation (@T_C=25°C)		32.2	W
	Derating factor above 25°C		0.26	W/°C
T_{STG}, T_J	Operating junction temperature & storage temperature		-55 ~ + 150	°C
T_L	Maximum lead temperature for soldering purpose, 1/8 from case for 5 seconds.		300	°C

*. Drain current is limited by junction temperature.

Thermal characteristics

Symbol	Parameter	Value	Unit
R_{thjc}	Thermal resistance, Junction to case	3.88	°C/W
R_{thja}	Thermal resistance, Junction to ambient	45.1	°C/W

Electrical characteristic (T_C = 25ºC unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV_{DSS}	Drain to source breakdown voltage	V_{GS}=0V, I_D=250uA	600			V
ΔBV_{DSS} / ΔT_J	Breakdown voltage temperature coefficient	I_D=250uA, referenced to 25ºC		0.67		V/ºC
I_{DSS}	Drain to source leakage current	V_{DS}=600V, V_{GS}=0V			1	uA
		V_{DS}=480V, T_C=125ºC			50	uA
I_{GSS}	Gate to source leakage current, forward	V_{GS}=30V, V_{DS}=0V			100	nA
	Gate to source leakage current, reverse	V_{GS}=-30V, V_{DS}=0V			-100	nA
On characteristics						
$V_{GS(TH)}$	Gate threshold voltage	V_{DS}=V_{GS}, I_D=250uA	2		5	V
$R_{DS(ON)}$	Drain to source on state resistance	V_{GS}=10V, I_D=8A		0.21	0.23	Ω
G_{fs}	Forward transconductance	V_{DS}=30V, I_D=8A		10		S
Dynamic characteristics						
C_{iss}	Input capacitance	V_{GS}=0V, V_{DS}=200V, f=1MHz		1530		pF
C_{oss}	Output capacitance			62		
C_{rss}	Reverse transfer capacitance			2.6		
$t_{d(on)}$	Turn on delay time	V_{DS}=300V, I_D=16A, R_G=25Ω, V_{GS}=10V (note 4,5)		21		ns
t_r	Rising time			48		
$t_{d(off)}$	Turn off delay time			77		
t_f	Fall time			35		
Q_g	Total gate charge	V_{DS}=520V, V_{GS}=10V, I_D=16A (note 4,5)		43		nC
Q_{gs}	Gate-source charge			13		
Q_{gd}	Gate-drain charge			19		

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			16	A
I_{SM}	Pulsed source current				48	A
V_{SD}	Diode forward voltage drop.	I_S=16A, V_{GS}=0V			1.4	V
t_{rr}	Reverse recovery time	I_S=16A, V_{GS}=0V, dI_F/dt=100A/us		347		ns
Q_{rr}	Reverse recovery charge			5.6		uC

※. Notes

1. Repeatitive rating : pulse width limited by junction temperature.
2. L = 37.5mH, I_{AS} = 4A, V_{DD} = 50V, R_G=25Ω, Starting T_J = 25ºC
3. I_{SD} ≤ 16A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Staring T_J =25ºC
4. Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%
5. Essentially independent of operating temperature.

Fig. 1. On-state characteristics

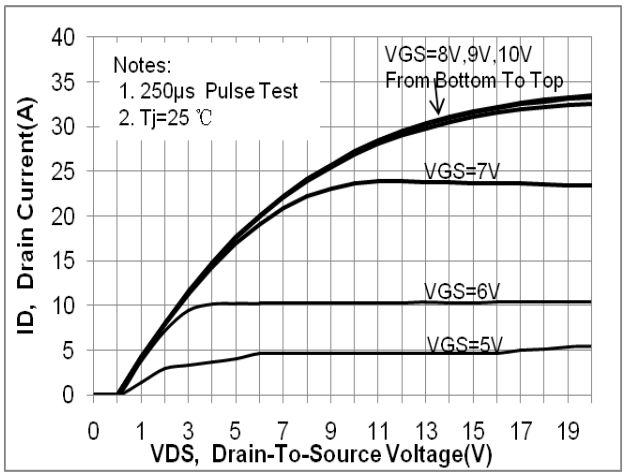


Fig. 2. On-resistance variation vs. drain current and gate voltage

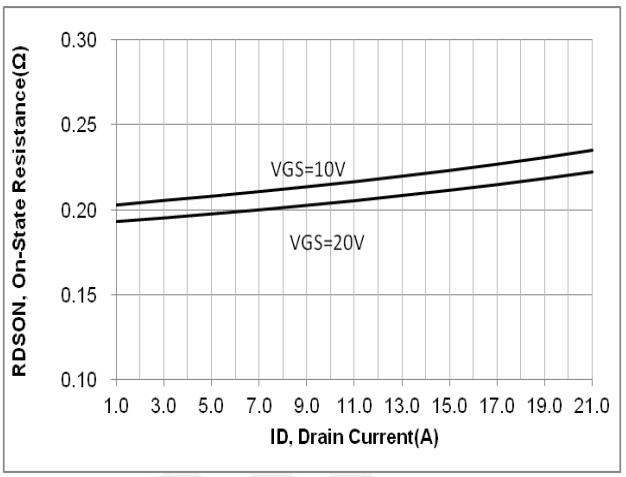


Fig. 3. Gate charge characteristics

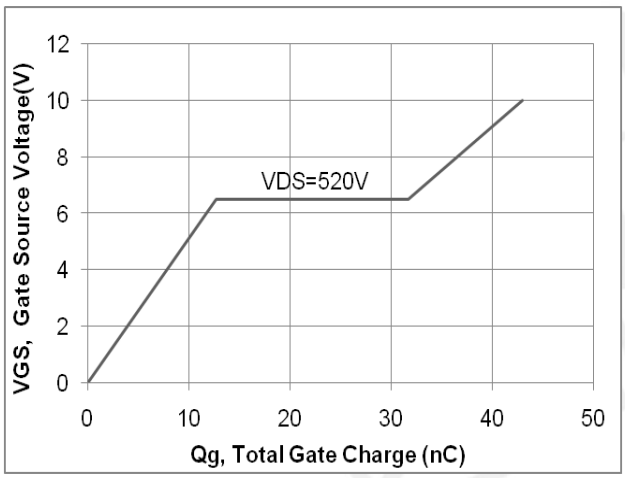


Fig. 4. On state current vs. diode forward voltage

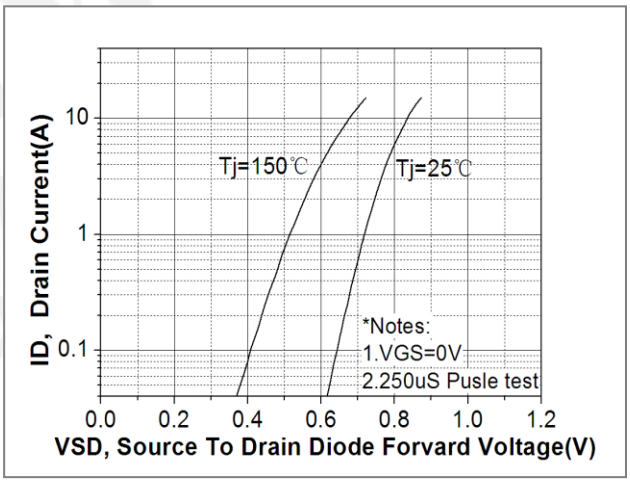


Fig 5. Breakdown Voltage Variation vs. Junction Temperature

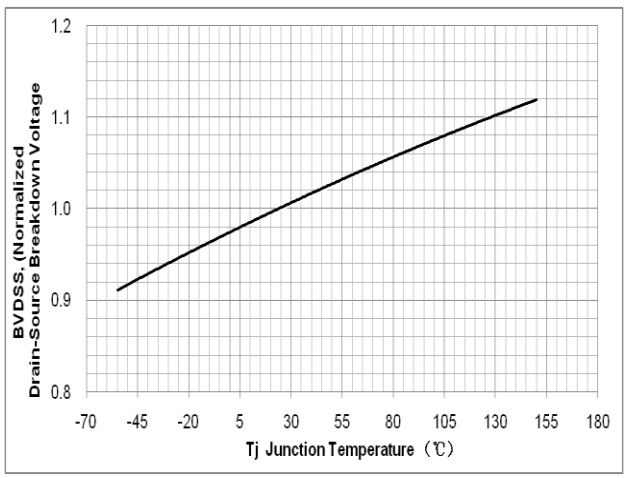


Fig. 6. On resistance variation vs. junction temperature

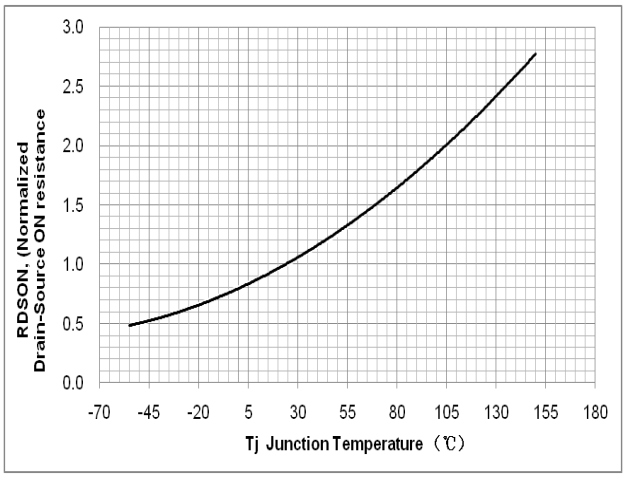


Fig. 7. Maximum safe operating area

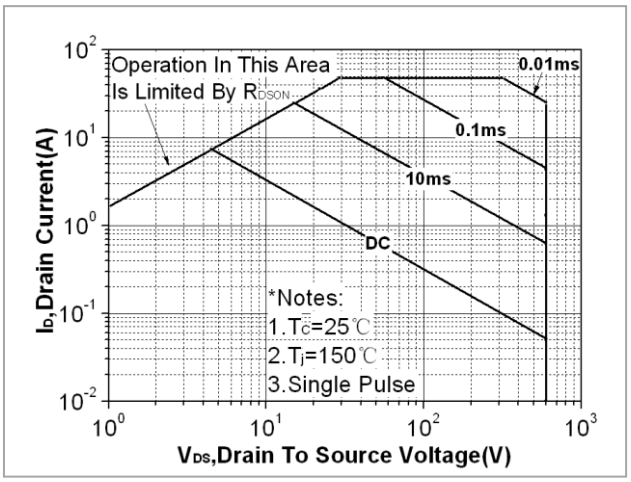


Fig. 8. Capacitance Characteristics

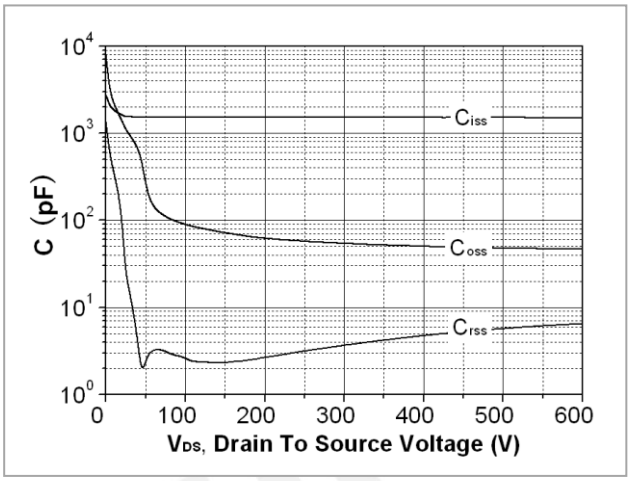


Fig. 9. Transient thermal response curve

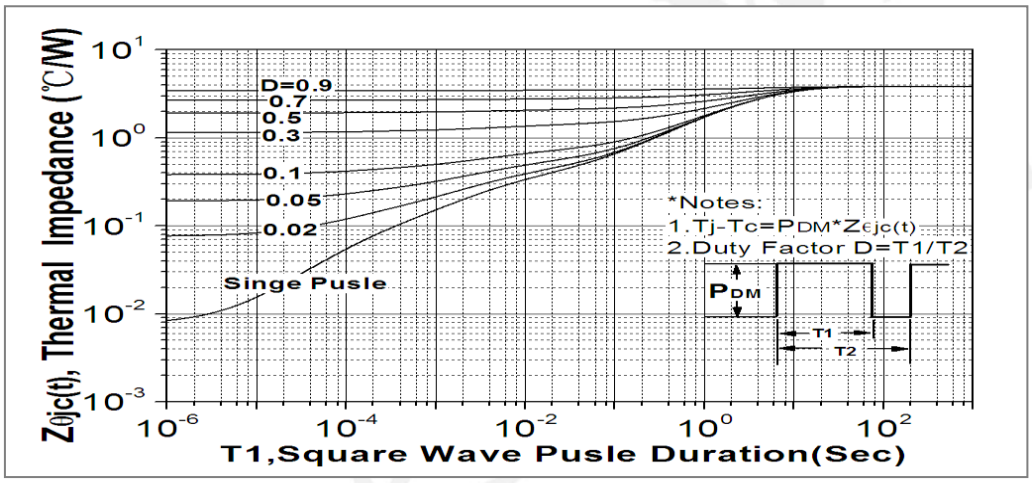
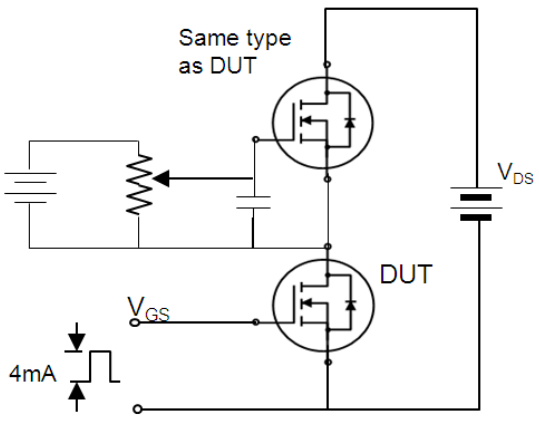


Fig. 10. Gate charge test circuit & waveform



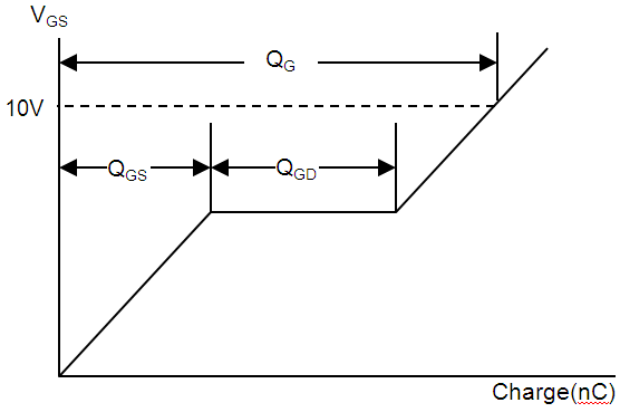


Fig. 11. Switching time test circuit & waveform

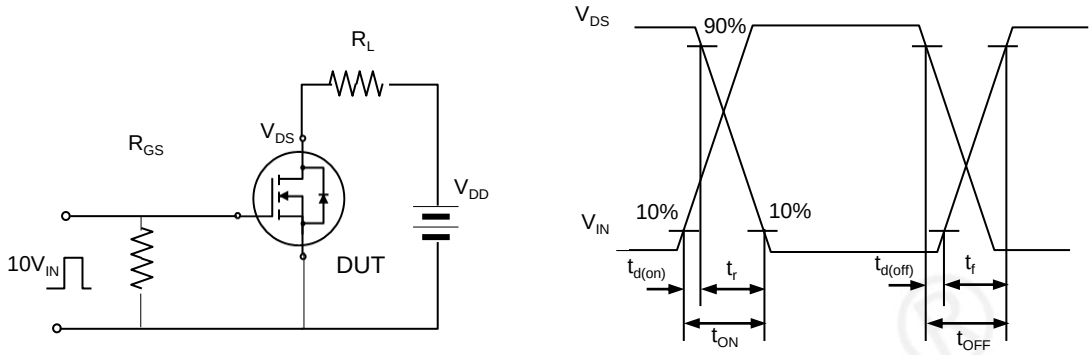


Fig. 12. Unclamped Inductive switching test circuit & waveform

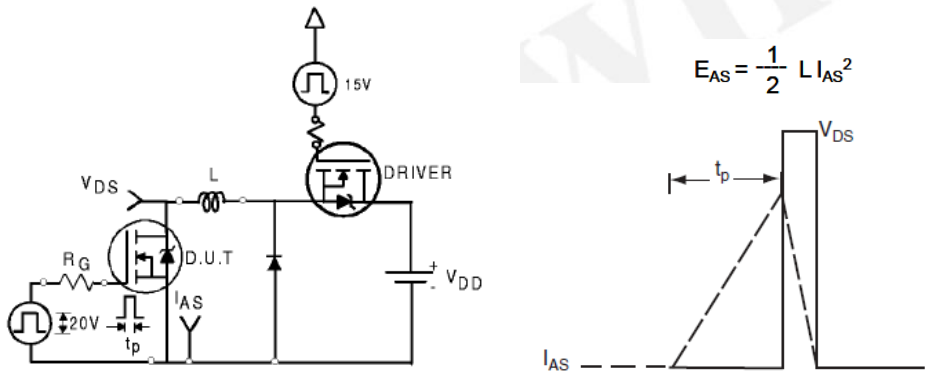
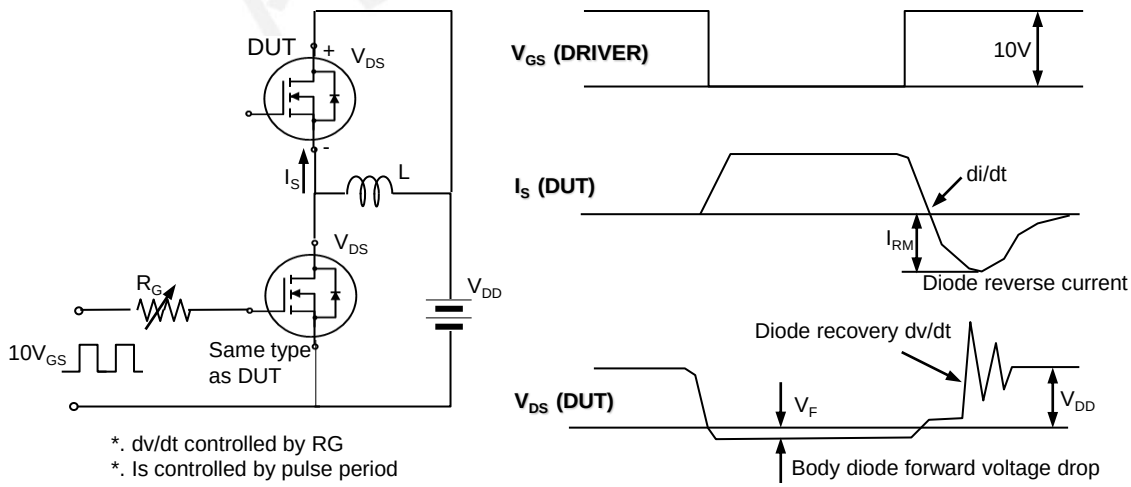


Fig. 13. Peak diode recovery dv/dt test circuit & waveform



DISCLAIMER

* All the data & curve in this document was tested in SEMIPOWER TESTING & APPLICATION CENTER.
* This product has passed the PCT,TC,HTRB,HTGB,HAST,PC and Solderdunk reliability testing.
* Qualification standards can also be found on the Web site (**http://www.semipower.com.cn**)
* Suggestions for improvement are appreciated, Please send your suggestions to **samwin@samwinsemi.com**